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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): Takashi Nagase Masayuki Miyabe Takashi Uetani Norihisa Sekimori Yoshitomo Teraoka Takanori Naito Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies) Name: Hakko Corporation Internal Address:

3. Nature of conveyance: Assignment Merger Security Agreement Change of Name Other Execution Date: February 16, 2004

Street Address: 4-5, Shiokusa, 2-chome, Naniwa-ku Osaka, JAPAN City: State: Zip: Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) 10/719,001 B. Patent No.(s) Additional numbers attached? Yes No

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) \$40.00 Enclosed Authorized to be charged to deposit account

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Douglas N. Larson, Esq. Squire, Sanders & Dempsey L.L.P. 801 South Figueroa Street 14th Floor Los Angeles, California 90017-5554

8. Deposit account number: 07-1853 (Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Douglas N. Larson, Reg. No. 29,401 February 20, 2004 Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and documents:

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

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**ASSIGNMENT**

WHEREAS, Takashi Nagase, residing at 7-2-13, Mamigaoka, Kashiba-city, Nara, Japan; Takashi Uetani, residing at 8-41-2, Ozaki-cho, Hannan-city, Osaka, Japan; Yoshitomo Teraoka, residing at 9-19-11 Tarui Sennan-city, Osaka, Japan; Takanori Naito, residing at 1-7-7-303 Ichiokamotomachi Minatoku Osaka-city, Osaka, Japan; Masayuki Miyabe, residing at 1-11-32-105 Shoutenshita Nishinariku Osaka-city, Osaka, Japan; and Norihisa Sekimori, residing at 4-14-16-401 Tezukayamanishi Sumiyoshiku Osaka-city, Osaka, Japan, the undersigned inventors and the ASSIGNORS herein, have made certain new and useful inventions in "SOLDERING IRON TIP AND METHOD OF MANUFACTURING SAME", for which we filed an application for Letters Patent of the United States, Application Serial No. 10/719,001, filed November 21, 2003, and of which inventions and improvements we are the owners; and

WHEREAS, Hakko Corporation, a corporation organized and existing under the laws of Japan, having a place of business at 4-5, Shiokusa, 2-chome, Naniwa-ku, Osaka, Japan, the ASSIGNEE herein, desires to acquire the entire right, title and interest in and to said inventions, applications and Letters Patent to be granted and issued thereon;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) by the ASSIGNEE to us paid, and other valuable consideration, the receipt and legal sufficiency of all of which is hereby acknowledged, we, the said ASSIGNORS, have sold and do hereby sell, assign, transfer and set over unto said ASSIGNEE, its successors and assigns, the entire right, title and interest in and to said inventions and all improvements thereon, in and to said application for Letters Patent thereon, in and to applications pertaining to or based upon said inventions and applications, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on said inventions and applications, or any of them, not only for, to and in the United States of America, its territories and possessions, but for, to and in all countries foreign thereto, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment.

And for the above-named considerations, we do hereby agree that we will, at the request of said ASSIGNEE, execute any and all applications for Letters Patent for said inventions and any and all other papers and documents and do all other and further lawful acts that said ASSIGNEE may deem necessary or desirable to obtain Letters Patent on said inventions, to secure the grant of such Letters Patent and to perfect and vest in the ASSIGNEE the entire right, title and interest in the inventions, applications and Letters Patent.

And for the above-named considerations, we do hereby authorize and empower the ASSIGNEE, its successors and assigns, to apply for and obtain, in its or their own names, Letters Patent for the said inventions before competent International Authorities and in any and all

countries foreign to the United States in which applications for Letters Patent can be so made or Letters Patent so obtained.

Dated: 16 / 02 / 2004 By T. Nagase  
Takashi Nagase

Dated: 16 / 02 / 2004 By Takashi Uetani  
Takashi Uetani

Dated: 16 / 02 / 2004 By Y. Teraoka  
Yoshitomo Teraoka

Dated: 16 / 02 / 2004 By Naitou  
Takanori Naito

Dated: 16 / 02 / 2004 By Miyabe  
Masayuki Miyabe

Dated: 16 / 02 / 2004 By N. Sekimori  
Norihisa Sekimori